

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

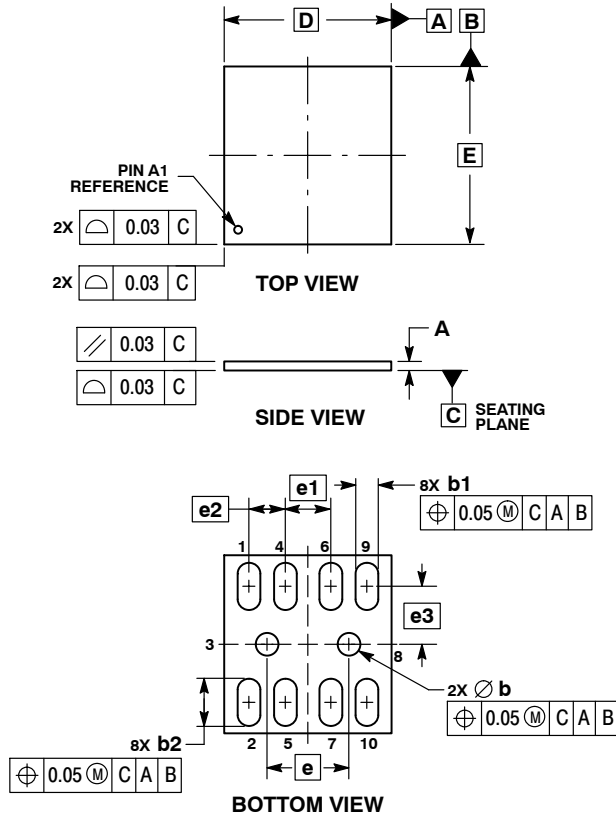
ON Semiconductor®



SCALE 4:1

WLCSP10 1.84x1.96x0.10
CASE 567PH
ISSUE A

DATE 06 APR 2017

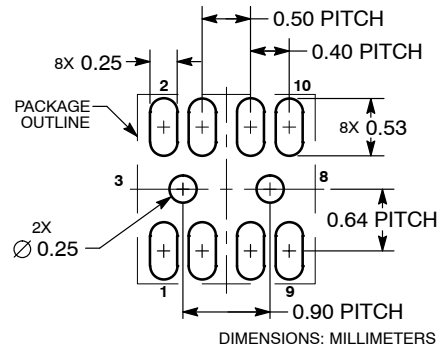


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.08	0.10	0.12
b	0.22	0.25	0.28
b1	0.22	0.25	0.28
b2	0.50	0.53	0.56
D	1.84 BSC		
E	1.96 BSC		
e	0.90 BSC		
e1	0.50 BSC		
e2	0.40 BSC		
e3	0.64 BSC		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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